PIC INTERNATIONAL CONFERENCE

2026 AGENDA

Correct as of 18-Apr-2026 11:36pm
For the latest version of our agenda, visit picinternational.net

Day 1 - Monday 20th April 2026

11:00	AngelTech Innovate Summit - Limited places! Requires separate registration: https://www.angeltech-innovate.net/register
18:00	Pre-conference Networking Drinks / Dinner Reception (available to those who have registered for 21st & 22nd April for AngelTech Conference)

Day 2 - Tuesday 21st April 2026

08:00 Registration and welcome refreshments

08:50 Housekeeping by Michael Lebby and David Cheskis - Conference Chairs

Foundations of PIC design: materials, devices and processes

09:00 Scaling Co-packaged Optics Requires a Fundamental Rethink of Fibre-to-chip Interconnects
Presented by Dominic Sulway - Light Trace Photonics

09:15 Advances in PIC Testing: Challenges and Measurement Needs from R&D to Volume Production
Presented by Marc-Andre Laliberte - APEX Technologies

09:30 From Design to Silicon: Foundry Solutions for Next-Gen Photonics ICs
Presented by Bowen Wang - Tower Semiconductor

09:45 Simulation-Driven PIC Design – Accelerating Performance, Reliability and Time-to-Market
Presented by Shin-Sung Kim - Ansys, part of Synopsys

10:00 Photonics Chip Level Test Strategies Overcoming Vibration Challenges in High Volume Production Environments
Presented by Nikta Jalayer - Physik

10:15 Glass-Integrated PICs: Shaping the Future of Photonics
Presented by Giacomo Corrielli - Ephos

10:30 Enabling High-Volume PIC Manufacturing through Interactive Verification & Data-Driven Design Workflows
Presented by Martin Fiers - Luceda Photonics

10:45 Morning Break and Networking

11:15 High‐Yield, High‐Volume TFLN Technology Using CMOS‐Compatible Processing
Presented by Bob van Someren - Rapid Photonics

11:30 LN-Based PICs: Novel Techniques for Structuring and Yield Improvements with Ion Beam Etching
Presented by Susanne Hartmann - scia Systems GmbH

11:45 New Materials for Enabling High-performance Photonic Devices and Emerging Applications
Presented by Leili Shiramin - imec

12:00 TFLN for CPO and Beyond
Presented by Hiroyuki Takanashi - Shincron Co. Ltd

12:15 How Co Packaged Optics Is Transforming Optical Test & Measurement
Presented by Matt Adams - VIAVI Solutions

12:30 Next-Generation Ultra-Low-Loss Integrated Photonics: From Mode-Locked Lasers to Traveling-Wave Amplifiers
Presented by Tobias Kippenberg - Swiss Federal Institute of Technology (EPFL)

12:45 Lunch Break and Networking

14:15 Startup Elevator Presentations

Connectivity and scalability for secure, high-speed data networks

Sponsored by OPTICA

14:25 PIC-enabled Quantum-safe Cryptography
Presented by Francesco Raffaelli - KETS Quantum Security

14:40 Building Scalable, Energy-Efficient TFLN PICs Through Industrial-Grade Manufacturing
Presented by Hernán Furci - CCRAFT

14:55 Beyond the Chip: System-Scale Simulations for Next-Gen PICs
Presented by Andrzej Po?atynski - VPIphotonics

15:10 Optics in AI Clusters: Innovation Mixed with Expediency
Presented by Roy Rubenstein - LightCounting

15:25 Afternoon Break and Networking

15:55 Integrated Optics in the Age of AI
Presented by Jochem Verbist - NVIDIA

16:10 Integrated Photonics from Opportunity to Mass Production for 50G+ Access Networks
Presented by Antonio Teixeira - PICadvanced

16:25 Enabling Network Scalability through Advanced Photonic Integration
Presented by Mehrdad Ziari - Nokia

16:40 Silicon Photonics Platform for Next-Generation Co-Packaged Optics and Optical I/O
Presented by Yoojin Ban - imec

16:55 From Lab to Volume: Scalable Active Alignment & Test Automation for PIC-Based Optical Transceivers
Presented by Tobias Müller - Aixemtec

17:10 Novel Startups in Photonic Integrated Circuits — From Concept to Deployment
Light Trace Photonics, KETS Quantum Security, InSpek, Alter Technology, and Uviquity

17:40 Closing Remarks

18:00 **Networking Drinks and Dinner Reception (concludes around 20:00)**

18:30 **AngelTech Rump Session - Bottlenecks & Battlegrounds: The Future of the AI Chip Ecosystem**
Presented by David Cheskis - Square Zero Technologies, and Diana Khlan - Chips Weekly

Day 3 - Wednesday 22nd April 2026

08:00 Registration and welcome refreshments

08:50 Housekeeping by Michael Lebby and David Cheskis - Conference Chairs

Future computing: PICs for photonic processing, quantum computers, and neural networks

09:00 PIC for Photonic Quantum Computing
Presented by Nicolas Maring - Quandela

09:15 System-Level Simulation: Towards Hardware–Software Co-Design for Photonics-Enabled AI Accelerators
Presented by Sébastien d'Herbais de Thun - Hewlett Packard Enterprise

09:30 Beyond Electronics with TFLN Photonic Integrated Circuits for Next-Generation Computing
Presented by Sep Mohajerani - Quantum Computing Inc

09:45 AIM Photonics / NY Creates PIC and Packaging Foundry for an End-to-End Approach to the Challenges in Photonic Integrated Circuits (PIC) and Packaging
Presented by David Harame - AIM Photonics

10:00 Morning Break and Networking

Foundations of PIC design: materials, devices and processes

10:30 Enabling THz Bandwidth on-chip with Plasmonic Modulators
Presented by Stephan Koch - Polariton Technologies AG

10:45 Advancing Scalable Photonic Integration: Heterogeneous Integration of Active Components for Next-Generation Applications
Presented by Michael Geiselmann - LIGENTEC

11:00 Aligned 2-Photon Grayscale Lithography for Free Space Microoptical Coupling in Photonic Packaging
Presented by Stephan Dottermusch - Nanoscribe

11:15 How Photonic Intelligent Manufacturing Enables Artificial Intelligence at Scale
Presented by Lorenzo Mandelli - ficonTEC

11:30 Scaling Integrated Photonics by Advancing Wafer Uniformity via Vacuum Technologies
Presented by Daniel de Sá Pereira - Buhler Group

11:45 Enabling Scalable Silicon Photonics Manufacturing Through Laser-Based Trimming and Cleaning
Presented by Simon Duval - Femtum

12:00 Convergence of Photonics and Electronics in Design
Presented by Xu Wang - Cadence

12:15 From Materials to Silicon Photonics PDKs: Scaling Foundry Platforms to 400G and Beyond
Presented by Robert Blum - Lightwave Logic

12:30 Lunch Break and Networking

Connectivity and scalability for secure, high-speed data networks

Sponsored by OPTICA

13:45 Designing for Yield: Production-Grade PDKs for Ultra-high-speed TFLN Photonic Engines
Presented by Amir Ghadimi - Lightium

14:00 Building the Fab of the Future: Scaling PIC Manufacturing Through Ecosystem Collaboration
Presented by Andre van de Geijn - Smart Photonics, and Bart Thiesen - Itility

14:15 Advancing Photonic Packaging and Integration Through UV Nanoimprint Lithography
Presented by Patrick Schuster - EV Group

14:30 Industry Ready Photonic Integration using Photonic Wire Bonds and Facet-Attached Micro-Lenses
Presented by Abdeslem Ben Hamida - Vanguard Automation

14:45 Photonic Integrated Circuits and Co-packaged Optics for HPC and AI Data Centers
Presented by Mika Takahashi - IDTechEx

15:00 Afternoon Break and Networking

Emerging applications: photonics for sensing, imaging and beyond

Sponsored by UpNano GmbH

15:30 From Fab to Solving Real‑World Challenges: Delivering 11 Real‑World Proof Points by 2029
Presented by Peter van Arkel - PhotonDelta

15:45 Enabling Foundry Ready BaTiO₃ Photonics: Advances and 300 mm Wafer Manufacturing
Presented by Sabina Hatch - DCA Instruments

16:00 All Glass Atomic-photonic Chips for Quantum Sensing and Metrology
Presented by Gianvito Lucivero - University of Bari/QSensAto

16:15 Multi-Wavelength Laser Sources for Scaling Datacenter Capacity
Presented by Amol Delmade - Pilot Photonics

16:30 Aluminum Nitride Photonic Integrated Circuits for Extending Nonlinear Photonics Applications to UV Spectrum
Presented by Scott Burroughs - Uviquity

16:45 Closing Remarks

PIC INTERNATIONAL CONFERENCE

ANGELTECH

NOTES